METHOD OF BENDING LEADS OF SEMICONDUCTOR PACKAGE

Abstract of the Disclosure

A method of bending a plurality of parallel leads of a semiconductor package, including placing the package on a die, positioning a supporting member such that each root portion is sandwiched between the lower side of the supporting member and the top surface of the die and loosely held therebetween, positioning a punch at a predetermined location, and linearly displacing the punch relative to the die so that each of the leads is bent in conformity with the shape of the working surface of the die.

Fig. 1